

Overview

HP ProBook 440 G8 Notebook PC



Left

- | | |
|--|--|
| 1. Internal Microphones (2) | 6. Clickpad |
| 2. Webcam LED (Optional) | 7. SuperSpeed USB Type-A 5Gbps signaling rate port |
| 3. HD and IR Camera (Optional) | 8. Ethernet Port (RJ-45) |
| 4. Camera Shutter (Only available with webcam) | 9. Nano Security Lock Slot (Lock sold separately) |
| 5. IR Camera LED (Optional) | |

Overview



Right

- | | |
|--|---|
| 1. Power Button Key | 6. HDMI Port (Cable not included) |
| 2. Power Connector | 7. Audio Combo Jack |
| 3. SuperSpeed USB Type-C® 10Gbps signaling rate (USB Power Delivery, DisplayPort™ 1.4) | 8. Micro SD Card Reader |
| 4. SuperSpeed USB Type-A 5Gbps signaling rate port | 9. Touch Fingerprint Sensor (select models) |
| 5. SuperSpeed USB Type-A 5Gbps signaling rate port | |

Overview

At a Glance

- A new compact design with lift-anywhere edge
- Choice of 11th generation Intel® Core™ i7, i5 and i3 processors
- Preinstalled with Windows 10 versions or FreeDOS
- Optional NVIDIA GeForce MX450 discrete graphics with 2 GB GDDR5 video memory
- Fast and upgradeable dual channel DDR4 SODIMM memory up to 32 GB
- Choice of 35.56 cm (14") diagonal HD, Ultra Wide Viewing Angle FHD, Touch or Non-Touch screen, and Privacy Panel option
- Features redesigned quiet and responsive HP Keyboard with the HP Programmable key and backlit options
- Choice of solid state drives up to 1 TB
- Multi-layered security with HP SureStart Gen6, HP Privacy Camera, HP Sure View Gen3¹, HP Sure Sense, HP Sure Click, and Touch Fingerprint reader²
- Supports wireless options for connectivity on the go including gigabit-speed Wi-Fi® 6 and CAT9 4G/LTE WWAN
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles³
- Designed to support HP docking options
- Passed MIL-STD 810H tests⁴
- Battery life up to 12 hours and 45 minutes

1. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

2. Sold separately or as an optional feature

3. HP notebooks up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

4. MIL STD 810H testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Technical Specifications

PRODUCT NAME

HP ProBook 440 G8 Notebook PC

OPERATING SYSTEMS

Preinstalled

Windows 10 Pro 64 – HP recommends Windows 10 Pro¹
Windows 10 Pro 64 (National Academic only)²
Windows 10 Home 64¹
Windows 10 Home Single Language 64¹
Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)¹
FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see <https://aka.ms/ProEducation> for Windows 10 Pro Education feature information.

Supported Versions

HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see <https://support.hp.com/document/c05195282>

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel[®] and AMD[®] 7th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on <http://www.support.hp.com>.

A full list of HP products and the Windows 10 versions tested is available on the HP support website. <https://support.hp.com/us-en/document/c05195282>.

PROCESSORS

Intel[®] Core[™] i7-1185G7 (3.0 GHz base frequency, up to 4.8 GHz with Intel[®] Turbo Boost Technology, 12 MB L3 cache, 4 cores)^{3,4,5,6}

Intel[®] Core[™] i7-1165G7 (2.8 GHz base frequency, up to 4.7 GHz with Intel[®] Turbo Boost Technology, 12 MB L3 cache, 4 cores)^{3,4,5,6}

Intel[®] Core[™] i5-1145G7 (2.6 GHz base frequency, up to 4.4 GHz with Intel[®] Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}

Intel[®] Core[™] i5-1135G7 (2.4 GHz base frequency, up to 4.2 GHz with Intel[®] Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}

Intel[®] Core[™] i3-1125G4 with Intel[®] UHD Graphics (2.0 GHz base frequency, up to 3.7 GHz with Intel[®] Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}

Intel[®] Core[™] i3-1115G4 with Intel[®] UHD Graphics (3.0 GHz base frequency, up to 4.1 GHz with Intel[®] Turbo Boost Technology, 6 MB L3 cache, 2 cores)^{3,4,5,6}

Intel[®] Pentium[®] Gold 7505 with Intel[®] UHD Graphics (2.0 GHz base frequency, up to 3.5 GHz with Intel[®] Turbo Boost Technology, 4 MB L3 cache, 2 cores)^{3,4,5,6}

Intel[®] Celeron[®] 6305 with Intel[®] UHD Graphics (1.8 GHz base frequency, 4 MB L3 cache, 2 cores)^{3,4,5,6}

Technical Specifications

Processors Family

11th Generation Intel® Core™ i7 processor (i7-1165G7)⁷

11th Generation Intel® Core™ i5 processor (i5-1135G7)⁷

11th Generation Intel® Core™ i3 processor (i3-1115G4)⁷

3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See <http://www.intel.com/technology/turboboost> for more information.

6. Max Boost clock frequency performance varies depending on hardware, software and overall system configuration.

7. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on <http://www.support.hp.com>.

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated

Intel® Iris® X^e Graphics (Core i5 and Core i7)³⁵

Intel® UHD Graphics (Core i3)

Discrete

NVIDIA® GeForce® MX450 (2 GB DDR5 dedicated)⁹

Supports

Support HD decode, DX12, HDMI 1.4b⁸

8. HD content required to view HD images.

9. Integrated graphics depends on processor. NVIDIA® Optimus™ technology requires an Intel processor, plus an NVIDIA® GeForce® discrete graphics configuration and is available on Windows 10 Pro OS. With NVIDIA® Optimus™ technology, full enablement of all discrete graphics video and display features may not be supported on all systems (e.g. OpenGL applications will run on the integrated GPU or the APU as the case may be).

35. Intel® Iris® Xe Graphics capabilities require system to be configured with Intel® Core™ i5 or i7 processors and dual channel memory. Intel® Iris® Xe Graphics with Intel® Core™ i5 or 7 processors and single channel memory will only function as UHD graphics.

Technical Specifications

DISPLAYS

Internal

Non-Touch

- 35.56 cm (14") diagonal HD SVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC (1366 x 768) ^{8,11}
- 35.56 cm (14") diagonal HD SVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC for HD camera (1366 x 768) ^{8,11}
- 35.56 cm (14") diagonal HD SVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC for HD+IR camera (1366 x 768) ^{8,11}
- 35.56 cm (14") diagonal HD SVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC for HD camera and WWAN (1366 x 768) ^{8,11}
- 35.56 cm (14") diagonal FHD UWVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC (1920 x 1080) ^{8,11}
- 35.56 cm (14") diagonal FHD UWVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC for HD camera (1920 x 1080) ^{8,11}
- 35.56 cm (14") diagonal FHD UWVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC for HD + IR camera (1920 x 1080) ^{8,11}
- 35.56 cm (14") diagonal FHD UWVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC for HD camera and WWAN (1920 x 1080) ^{8,11}
- 35.56 cm (14") diagonal FHD UWVA eDP+PSR anti-glare, low power narrow bezel bent, 400 nits, 100% sRGB for HD camera (1920 x 1080) ^{8,11}
- 35.56 cm (14") diagonal FHD UWVA eDP+PSR anti-glare, low power narrow bezel bent, 400 nits, 100% sRGB for HD+IR camera (1920 x 1080) ^{8,11}
- 35.56 cm (14") diagonal FHD UWVA eDP+PSR anti-glare, narrow bezel bent with HP Sure View Gen3 Integrated Privacy Screen, 1000 nits, 100% sRGB for HD camera (1920 x 1080) ^{8,11, 12}
- 35.56 cm (14") diagonal FHD UWVA eDP+PSR anti-glare, narrow bezel bent with HP Sure View Gen3 Integrated Privacy Screen, 1000 nits, 100% sRGB for HD+IR camera (1920 x 1080) ^{8,11, 12}

Touch

- 35.56 cm (14") diagonal FHD UWVA eDP anti-glare, narrow bezel bent, touch-on-panel screen, 250 nits, 45% NTSC for HD camera (1920 x 1080) ^{8,10,11}
- 35.56 cm (14") diagonal FHD UWVA eDP anti-glare, narrow bezel bent, touch-on-panel screen, 250 nits, 45% NTSC for HD camera and WWAN (1920 x 1080) ^{8,10,11}

HDMI

Supports resolutions up to 4K 30Hz

- 8. HD content required to view HD images.
- 10. Sold separately or as an optional feature.
- 11. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 12. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

NOTE: Actual brightness will be lower with touchscreen or Sure View.

Technical Specifications

STORAGE AND DRIVES

Primary M.2 Storage

- 128 GB PCIe® NVMe™ M.2 TLC Solid State Drive ¹³
- 256 GB PCIe® NVMe™ M.2 Value Solid State Drive ¹³
- 512 GB PCIe® NVMe™ M.2 Value Solid State Drive ¹³
- 512 GB Intel® PCIe® NVMe™ QLC M.2 SSD with 32 GB Intel® Optane™ memory H10 ^{13, 39, 40}
- 1 TB PCIe® NVMe™ M.2 TLC Solid State Drive ¹³

13. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

39. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or higher Intel® Core™ processor, BIOS version with Intel® Optane™ supported, Windows 10 64-bit, and an Intel® Rapid Storage Technology (Intel® RST) driver.

40. Intel® Optane™ memory H10 only for Intel® PCIe® NVMe™ QLC M.2 SSD.

MEMORY

Maximum Memory

32 GB DDR4-3200 SDRAM ¹⁴

Memory*

- 32 GB DDR4-3200 SDRAM (2 x 16 GB) ¹⁴
- 16 GB DDR4-3200 SDRAM (1 x 16 GB) ¹⁴
- 12 GB DDR4- 3200 SDRAM (4 GB and 8 GB (1 x 8 GB)) ¹⁴
- 8 GB DDR4-3200 SDRAM (1 x 8 GB) ¹⁴
- 8 GB DDR4-3200 SDRAM (2 x 4 GB) ¹⁴
- 4 GB DDR4-3200 SDRAM (1 x 4 GB) ¹⁴

Memory Slots

2 SODIMM

Both slots are accessible/upgradeable by IT or self-maintainers only

DDR4 PC4 SODIMMS, system runs at 3200

Supports Dual Channel Memory

14. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

Technical Specifications

NETWORKING/COMMUNICATIONS

WLAN

Realtek 802.11ac (2x2) WLAN and Bluetooth® 5 Combo ¹⁵

Intel® Dual Band Wireless-AC 9560 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth® 5 Combo, non-vPro® ¹⁵

Intel® Dual Band Wi-Fi® 6 AX201 802.11a/b/g/n/ac/ax (2x2) WLAN and Bluetooth® 5 Combo, non-vPro® ¹⁸

Realtek RTL8852AE 802.11ax 2x2 Wi-Fi and Bluetooth® 5.1 ¹⁸

WWAN

Intel® XMM™ 7360 LTE-Advanced (Cat9) ¹⁶

Ethernet

Realtek 10/100/1000 GbE NIC ¹⁷

15. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi® 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

16. WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

17. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

18. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for Wi-Fi® 6 (802.11ax WLAN) are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

AUDIO/MULTIMEDIA

Audio

2 Integrated stereo speakers

Integrated microphone (Dual Array)

Speaker Power

2W/4ohm Per speaker

Camera

720p HD Camera⁸

720p HD Camera+IR Camera^{8,10}

8. HD content required to view HD images.

10. Sold separately or as an optional feature.

Technical Specifications

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant and optional Durakeys and backlit

Pointing Device

Clickpad with multi-touch gesture support

Function Keys

F1 - Display Switching

F2 - Blank or SureView On/Off

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Blank or Backlit Toggle

F10 - Insert

F11 - Airplane Mode

F12 - Programmable Key

Print Screen

Power Button (with LED)

Hidden Function Keys

Fn+R - Break

Fn+S - Sys Rq

Fn+C - Scroll Lock

SOFTWARE AND SECURITY

Preinstalled Software

BIOS

HP BIOSphere Gen5 ¹⁹

HP Drive Lock & Automatic Drive Lock

BIOS Update via Network

Power On Authentication

HP Secure Erase ²¹

Absolute Persistence Module ²²

HP LAN-Wireless Protection

Pre-boot Authentication

Software

Xerox® DocuShare® 30 day free trial offer⁴¹

HP Connection Optimizer ²⁰

HP Image Assistant

HP Hotkey Support

myHP

HP Noise Cancellation Software

Technical Specifications

HSA Fusion for Commercial
HSA Telemetry for Commercial
Touchpoint Customizer for Commercial
HP Notifications
HP Privacy Settings
HP System Information
HP Wireless Button Driver
HP Power Manager
HP Work Well
Buy Office (sold separately)

Manageability Features

HP Driver Packs (download) ²³
HP Manageability Integration Kit Gen3 (download) ²⁴
HP System Software Manager (SSM) (download)
HP BIOS Config Utility (BCU) (download)
HP Client Catalog (download)
HP Client Management Script Library (download)

Client Security Software

HP Client Security Manager Gen7 ²⁵
Windows Defender ²⁶

Security Management

Pre-boot Authentication
USB enable/disable (via BIOS)
Power-on password (via BIOS)
Setup password (via BIOS)
HP Fingerprint Sensor ²⁷
Support for chassis padlocks and cable lock devices
HP Sure Click ²⁸
HP Sure Sense ²⁹
HP Sure Start Gen6 ³⁰
HP Sure Admin ³¹
TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified) ³²

19. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.

20. HP Connection Optimizer requires Windows 10.

21. HP Secure Erase For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.

22. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: <https://www.absolute.com/about/legal/agreements/absolute/>

23. HP Driver Packs not preinstalled, however available for download at <http://www.hp.com/go/clientmanagement>.

24. HP Manageability Integration Kit can be downloaded from <http://www.hp.com/go/clientmanagement>.

25. HP Client Security Manager Gen6 requires Windows and is available on the select HP Pro and Elite PCs.

Technical Specifications

- 26. Windows Defender Opt in and internet connection required for updates.
- 27. HP Fingerprint sensor is an optional feature that must be configured at purchase.
- 28. HP Sure Click requires Windows 10 Pro or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.
- 29 HP Sure Sense requires Windows 10 Pro or Enterprise.
- 30. HP Sure Start Gen6 is available on select HP PCs.
- 31. HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from <http://www.hp.com/go/clientmanagement> and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.
- 32. Firmware TPM is version 2.0.
- 41. Simply sign up and start using Xerox® DocuShare® Go. No credit card. No obligation. Data will become unavailable unless a subscription is entered before the end of the 30-day free trial period. See visit <http://www.xerox.com/docusharego> for details.

POWER

Power Supply ¹⁶

- HP Smart 65 W External AC power adapter ³²
- HP Smart 65 W EM External AC power adapter ³²
- HP Smart 65 W USB Type-C® adapter ³²
- HP Smart 45 W External AC power adapter ³²
- HP Smart 45 W USB Type-C® adapter ³²

Primary Battery

- HP Long Life 3-cell, 45 Wh Polymer ³³

Power Cord

- 3-wire plug - 1m ³³
- 2-wire plug - 1m ³³

Battery life

- Up to 12 hours and 45 minutes (UMA graphics, Intel® 11th generation CPU and 3-cell 45 WHr battery)

Battery Weight

- 190 g

- 32. Availability may vary by country.
- 33. Battery is internal and not replaceable by customer. Serviceable by warranty.

Technical Specifications

WEIGHTS & DIMENSIONS

Product Weight ³⁴

Starting at 3.03 lb

Starting at 1.38 kg

Product Dimensions (w x d x h)

32.19 x 21.39 x 1.99 cm

12.68 x 8.42 x 0.78 in

34. Weight will vary by configuration.

PORTS/SLOTS

Ports

1 SuperSpeed USB Type-C® 10Gbps signaling rate (USB Power Delivery, DisplayPort™ 1.4)

3 SuperSpeed USB Type-A 5Gbps signaling rate (1 charging, 1 powered port)

1 HDMI 1.4b ³⁶

1 RJ-45

1 Headphone/microphone combo jack

1 AC power

Expansion Slots

1 Micro SD Card Reader

Supports SD, SDHC, SDXC

36. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 3-year and 1-year limited warranties and 90-day software limited warranty options depending on country. Batteries have a default one-year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to <http://www.hp.com/support/batterywarranty/> for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <http://www.hp.com/go/cpc>.³⁷

37. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit <http://www.hp.com/go/cpc>. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Technical Specifications

ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations	<p>This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:</p> <ul style="list-style-type: none"> •IT ECO declaration •US ENERGY STAR® •EPEAT® 2019 Gold in U.S. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information. 		
System Configuration	<p>The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a “Typically Configured Notebook”.</p>		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	4.14 W	4.164 W	4.056 W
Normal Operation (Long idle)	2.112 W	2.184 W	2.076 W
Sleep	0.372 W	0.384 W	0.372 W
Off	0.192 W	0.228 W	0.192 W
	<p>Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.</p>		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	14 BTU/hr	14 BTU/hr	14 BTU/hr
Normal Operation (Long idle)	7 BTU/hr	7 BTU/hr	7 BTU/hr
Sleep	1 BTU/hr	1 BTU/hr	1 BTU/hr
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr
	<p>Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.</p>		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)	
Typically Configured – Idle	2.6	14.4	
Fixed Disk – Random writes	2.6	14.4	
Longevity and Upgrading	<p>This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:</p> <ul style="list-style-type: none"> • 3 USB ports • 1 PC card slot (type I/II) 		

Technical Specifications

	<ul style="list-style-type: none"> • 1 ExpressCard/54 slot • 1 IEEE 1394 Port • 2 SODIMM memory slots • Optional expansion base docking station • 1 multi-bay II storage port <p>Spare parts are available throughout the warranty period and or for up to “5” years after the end of production.</p>		
Batteries	<p>This battery(s) in this product comply with EU Directive 2006/66/EC</p> <p>Batteries used in the product do not contain: Mercury greater the 1ppm by weight Cadmium greater than 20ppm by weight</p> <p>Battery size: Not Applicable Battery type: Not Applicable</p>		
Additional Information	<ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the <Gold> level, see http://www.epeat.net • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 2.4% post-consumer recycled plastic (by wt.) • This product is 96.2% recycle-able when properly disposed of at end of life. 		
Packaging Materials	External:	PAPER/Paper	51 g
		PAPER/Corrugated	230 g
	Internal:	PLASTIC/Polyethylene Expanded - EPE	31 g
		PLASTIC/Polyethylene low density - LDPE	9 g
Material Usage	<p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates 		

Technical Specifications

	<ul style="list-style-type: none"> • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	<p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	<p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p>
HP Inc. Corporate Environmental Information	<p>For more information about HP's commitment to the environment:</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p>

Technical Specifications

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)

Nominal Operating Voltage	19 V
Average Operating Power	4.62 W
Integrated graphics	Yes
Discrete Graphics	N185-G5: 25W
Max Operating Power	Discrete < 65W UMA < 45W

Temperature

Operating	32° to 95° F (0° to 35° C)
Non-operating	-4° to 140° F (-20° to 60° C)

Relative Humidity

Operating	10% to 90%, non-condensing
Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock

Operating	40 G, 2 ms, half-sine
Non-operating	200 G, 2 ms, half-sine

Random Vibration

Operating	0.75 grms
Non-operating	1.50 grms

Altitude (unpressurized)

Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)

Planned Industry Standard Certifications

UL	Yes
CSA	Yes
FCC Compliance	Yes
ENERGY STAR®	Select models ³⁸
EPEAT®	EPEAT® 2019 Gold in U.S. ³⁹
ICES	Yes
Australia /	Yes
NZ A – Tick Compliance	Yes
CCC	Yes
Japan VCCI Compliance	Yes
KC	Yes
BSMI	Yes
CE Marketing Compliance	Yes
BNCI or BELUS	Yes
CIT	Yes
GOST	Yes

Technical Specifications

Saudi Arabian Compliance (ICCP)	Yes
SABS	Yes

38. Configurations of the HP ProBook 440 G8 that are ENERGY STAR® certified are identified as HP ProBook 440 G8 ENERGY STAR on HP websites and on <http://www.energystar.gov>.

39. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit <http://www.epeat.net> for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Actual brightness will be lower with touchscreen or Sure View.

Panel LCD 14 inch FHD (1920x1080) Anti-Glare WLED UWVA 45% NTSC 250nits eDP 1.2 w/o PSR bent NWBZ	Outline Dimensions (W x H x D)	316.17 x 186.4 mm (max) (w/ PCB)
	Active Area	309.37 x 174.02 mm (typ.)
	Weight	300 g (max)
	Diagonal Size	14.0 inch
	Thickness	3.0 mm/ 5.0 mm (PCB) (max)
	Interface	eDP 1.2
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60 Hz
	Brightness	250 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format	RGB Stripe
	Backlight	LED
	Color Gamut Coverage	NTSC 45%
	Color Depth	6 bits (Hi FRC supportive w/ condition to enable)
Viewing Angle	UWVA 85/85/85/85	

Panel LCD 14 inch FHD (1920x1080) Anti-Glare WLED UWVA 45% NTSC 250nits eDP 1.2 w/o PSR bent Touch on Panel NWBZ	Outline Dimensions (W x H x D)	316.17 x 186.4 mm (max) (w/ PCB)
	Active Area	309.37 x 174.02 mm (typ.)
	Weight	305 g (max)
	Diagonal Size	14.0 inch
	Thickness	3.0 mm/ 5.0 mm (PCB) (max)
	Interface	eDP 1.2
	Surface Treatment	Anti-Glare On-cell
	Touch Enabled	Yes
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60 Hz
	Brightness	250 nits
	Pixel Resolution	1920 x 1080 (FHD)

Technical Specifications

Format	RGB Stripe
Backlight	LED
Color Gamut Coverage	NTSC 45%
Color Depth	6 bits (Hi FRC supportive w/ condition to enable)
Viewing Angle	UWVA 85/85/85/85

Panel LCD 14 inch FHD (1920x1080) Anti-Glare WLED UWVA 72% NTSC 1000nits eDP 1.4+PSR2 bent Privacy NB2X Gen3

Outline Dimensions (W x H x D)	315.31 x 186.48 mm (max.)
Active Area	309.31 x 173.99
Weight	220 g (max)
Diagonal Size	14.0 inch
Thickness	3.9 mm (max)
Interface	eDP 1.4 + PSR (4 lane)
Surface Treatment	Anti-Glare (AG)
Touch Enabled	No
Contrast Ratio	2001:1 (typ.)
Refresh Rate	60 Hz
Brightness	1000 nits
Pixel Resolution	3840 x 2160 (UHD)
Format	RGB
Backlight	LED
Color Gamut Coverage	sRGB 100%
Color Depth	8 bits
Viewing Angle	UWVA 85/85/85/85

Panel LCD 14 inch FHD (1920x1080) Anti-Glare WLED UWVA sRGB 100% NTSC 400nits eDP 1.4+PSR2 bent LP NB2X

Outline Dimensions (W x H x D)	315.31 x 186.48 mm (max)
Active Area	309.312 x 173.988 mm (typ.)
Weight	220 g (max)
Diagonal Size	14.0 inch
Thickness	3.9 mm (max)
Interface	eDP 1.4 + PSR (4 lane)
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	1200:1 (typ.)
Refresh Rate	60 Hz
Brightness	400 nits
Pixel Resolution	1920 x 1080 (FHD)
Format	RGB
Backlight	LED
Color Gamut Coverage	sRGB 100%
Color Depth	6 bits
Viewing Angle	UWVA 85/85/85/85

Technical Specifications

Panel LCD 14-in HD (1366x768) Anti-Glare WLED SVA 45% NTSC 250nits eDP 1.2 w/o PSR NWBZ bent	Outline Dimensions (W x H x D)	316.1 x 186.37 (mm) max
	Active Area	309.4 x 173.95 (mm)
	Weight	300g Max
	Diagonal Size	14.0 inch
	Thickness	3.2mm (panel) / 5.0mm (panel+PCB) max.
	Interface	eDP 1.2 (1 lane)
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	300:1 (typ)
	Refresh Rate	60 Hz
	Brightness	250 nits
	Pixel Resolution	1366 x 768 (HD)
	Format	RGB
	Backlight	LED
	Color Gamut Coverage	NTSC 45%
	Color Depth	6 bits
	Viewing Angle	SVA 45/45/15/35

Technical Specifications

STORAGE AND DRIVES*

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

SSD 128GB 2280 PCIe-3x2 Three Layer Cell	Form Factor	M.2 2280
	Capacity	128 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe
	Maximum Sequential Read	1400 ~ 2100 MB/s
	Maximum Sequential Write	800 ~ 1200 MB/s
	Logical Blocks	250,069,680
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; DIPM; TRIM; DEVSLP	

SSD 1TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided	Form Factor	M.2 2280
	Capacity	1 TB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	3100 ~ 3500 MB/s
	Maximum Sequential Write	2770 ~ 3037 MB/s
	Logical Blocks	2,000,409,264
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; TRIM; L1.2	

SSD 256GB 2280 PCIe NVMe Value	Form Factor	M.2 2280
	Capacity	256 GB
	NAND Type	Value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3
	Maximum Sequential Read	2100 ~ 2200 MB/s
	Maximum Sequential Write	900 ~ 1400 MB/s
	Logical Blocks	500,118,192

Technical Specifications

Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security (optional); TRIM; L1.2

SSD 512GB 2280 PCIe NVMe Value	Form Factor	M.2 2280
	Capacity	512 GB
	NAND Type	Value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3
	Maximum Sequential Read	2200 ~ 2300 MB/s
	Maximum Sequential Write	1000 ~ 1600 MB/s
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security (optional); TRIM; L1.2	

SSD 512GB 2280 PCIe-3x2x2 NVMe+SSD 32GB 3D Xpoint	Form Factor	M.2 2280
	Capacity	512 GB
	NAND Type	QLC+3D XPoint
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X2X2
	Maximum Sequential Read	Up to 2400 MB/s
	Maximum Sequential Write	Up to 1300 MB/s
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; TRIM; L1.2	

Technical Specifications

NETWORKING/COMMUNICATIONS

Intel Wi-Fi® 6¹ AX201 + Bluetooth® 5 (802.11ax 2x2, non-vPro®, supporting gigabit file transfer speeds)⁵ non-vPro®	Wireless LAN Standards	<ul style="list-style-type: none"> IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Features Wi-Fi® 6 technology
	Frequency Band	<ul style="list-style-type: none"> • 802.11b/g/n/ax 2.402 – 2.482 GHz • 802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	<ul style="list-style-type: none"> • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS0 ~ MCS15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) • 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security³	<ul style="list-style-type: none"> • IEEE compliant 64 /128-bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power²	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum

Technical Specifications

	<ul style="list-style-type: none"> • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum • 802.11ax HT40(2.4GHz): +10dBm minimum • 802.11ax VHT160(5GHz): +10dBm minimum 				
Power Consumption	<ul style="list-style-type: none"> • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW 				
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode				
Receiver Sensitivity³	<ul style="list-style-type: none"> • 802.11b, 1Mbps: -93.5dBm maximum • 802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum • 802.11ax, MCS11(HT40): -59dBm maximum • 802.11ax, MCS11(VHT160): -58.5dBm maximum 				
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth® communications				
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface				
Dimensions	<ol style="list-style-type: none"> 1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm 				
Weight	<ol style="list-style-type: none"> 1. Type 2230: 2.8 g 2. Type 126: 1.3 g 				
Operating Voltage	3.3v +/- 9%				
Temperature	<table> <tbody> <tr> <td>Operating</td> <td>14° to 158° F (-10° to 70° C)</td> </tr> <tr> <td>Non-operating</td> <td>-40° to 176° F (-40° to 80° C)</td> </tr> </tbody> </table>	Operating	14° to 158° F (-10° to 70° C)	Non-operating	-40° to 176° F (-40° to 80° C)
Operating	14° to 158° F (-10° to 70° C)				
Non-operating	-40° to 176° F (-40° to 80° C)				
Humidity	<table> <tbody> <tr> <td>Operating</td> <td>10% to 90% (non-condensing)</td> </tr> <tr> <td>Non-operating</td> <td>5% to 95% (non-condensing)</td> </tr> </tbody> </table>	Operating	10% to 90% (non-condensing)	Non-operating	5% to 95% (non-condensing)
Operating	10% to 90% (non-condensing)				
Non-operating	5% to 95% (non-condensing)				
Altitude	<table> <tbody> <tr> <td>Operating</td> <td>0 to 10,000 ft (3,048 m)</td> </tr> <tr> <td>Non-operating</td> <td>0 to 50,000 ft (15,240 m)</td> </tr> </tbody> </table>	Operating	0 to 10,000 ft (3,048 m)	Non-operating	0 to 50,000 ft (15,240 m)
Operating	0 to 10,000 ft (3,048 m)				
Non-operating	0 to 50,000 ft (15,240 m)				
LED Activity	LED Amber – Radio OFF LED Off – Radio ON				

HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0/5.1 Wireless Technology**Bluetooth® Specification** 4.0/4.1/4.2/5.0/5.1 Compliant

Technical Specifications

Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate* 2.17 Mbps BLE: 1 Mbps signaling data rate* 0.2 Mbps * Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth® Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for Wi-Fi® 6 (802.11ax WLAN) are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

Technical Specifications

3. Check latest software/driver release for updates on supported security features.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
5. Wi-Fi® supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160MHz channels.

Intel Jefferson Peak2 9560 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5.0 Combo¹ non-vPro®	Wireless LAN Standards	<ul style="list-style-type: none"> IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi® CERTIFIED modules
	Frequency Band	<ul style="list-style-type: none"> • 802.11b/g/n 2.402 – 2.482 GHz • 802.11a/n/ac 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	<ul style="list-style-type: none"> • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security³	<ul style="list-style-type: none"> • IEEE and Wi-Fi® compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power²	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum

Technical Specifications

	<ul style="list-style-type: none"> • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum 				
Power Consumption	<ul style="list-style-type: none"> • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW 				
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode				
Receiver Sensitivity⁴	<ul style="list-style-type: none"> • 802.11b, 1Mbps: -93.5dBm maximum • 802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum 				
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth® communications				
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface				
Dimensions	<ol style="list-style-type: none"> 1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm 				
Weight	<ol style="list-style-type: none"> 1. Type 2230: 2.8 g 2. Type 126: 1.3 g 				
Operating Voltage	3.3v +/- 9%				
Temperature	<table border="0"> <tr> <td>Operating</td> <td>14° to 158° F (-10° to 70° C)</td> </tr> <tr> <td>Non-operating</td> <td>-40° to 176° F (-40° to 80° C)</td> </tr> </table>	Operating	14° to 158° F (-10° to 70° C)	Non-operating	-40° to 176° F (-40° to 80° C)
Operating	14° to 158° F (-10° to 70° C)				
Non-operating	-40° to 176° F (-40° to 80° C)				
Humidity	<table border="0"> <tr> <td>Operating</td> <td>10% to 90% (non-condensing)</td> </tr> <tr> <td>Non-operating</td> <td>5% to 95% (non-condensing)</td> </tr> </table>	Operating	10% to 90% (non-condensing)	Non-operating	5% to 95% (non-condensing)
Operating	10% to 90% (non-condensing)				
Non-operating	5% to 95% (non-condensing)				
Altitude	<table border="0"> <tr> <td>Operating</td> <td>0 to 10,000 ft (3,048 m)</td> </tr> <tr> <td>Non-operating</td> <td>0 to 50,000 ft (15,240 m)</td> </tr> </table>	Operating	0 to 10,000 ft (3,048 m)	Non-operating	0 to 50,000 ft (15,240 m)
Operating	0 to 10,000 ft (3,048 m)				
Non-operating	0 to 50,000 ft (15,240 m)				
LED Activity	LED Amber – Radio OFF LED Off – Radio ON				

HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth® Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz

Technical Specifications

Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate* throughput up to 2.17 Mbps BLE: 1 Mbps signaling data rate* throughput up to 0.2 Mbps * Actual throughput may vary.
Transmit Power	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth® Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi® 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi® 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Wi-Fi® supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160 MHz channels.

Technical Specifications

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
3. Check latest software/driver release for updates on supported security features.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Realtek RTL8822CE 802.11ac 2x2 Wi-Fi® + Bluetooth® 5	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi® CERTIFIED modules
	Frequency Band	<ul style="list-style-type: none"> • 802.11b/g/n 2.402 – 2.482 GHz • 802.11a/n/ac 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	<ul style="list-style-type: none"> • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security³	<ul style="list-style-type: none"> • IEEE and Wi-Fi® compliant 64 / 128-bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points

Technical Specifications

Output Power²	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum 				
Power Consumption	<ul style="list-style-type: none"> • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW 				
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode				
Receiver Sensitivity⁴	<ul style="list-style-type: none"> • 802.11b, 1Mbps: -93.5dBm maximum • 802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum 				
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth® communications				
Form Factor	PCI-Express M.2 MiniCard				
Dimensions	<ol style="list-style-type: none"> 1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm 				
Weight	<ol style="list-style-type: none"> 1. Type 2230: 2.8 g 2. Type 126: 1.3 g 				
Operating Voltage	3.3v +/- 9%				
Temperature	<table> <tr> <td>Operating</td> <td>14° to 158° F (-10° to 70° C)</td> </tr> <tr> <td>Non-operating</td> <td>-40° to 176° F (-40° to 80° C)</td> </tr> </table>	Operating	14° to 158° F (-10° to 70° C)	Non-operating	-40° to 176° F (-40° to 80° C)
Operating	14° to 158° F (-10° to 70° C)				
Non-operating	-40° to 176° F (-40° to 80° C)				
Humidity	<table> <tr> <td>Operating</td> <td>10% to 90% (non-condensing)</td> </tr> <tr> <td>Non-operating</td> <td>5% to 95% (non-condensing)</td> </tr> </table>	Operating	10% to 90% (non-condensing)	Non-operating	5% to 95% (non-condensing)
Operating	10% to 90% (non-condensing)				
Non-operating	5% to 95% (non-condensing)				
Altitude	<table> <tr> <td>Operating</td> <td>0 to 10,000 ft (3,048 m)</td> </tr> <tr> <td>Non-operating</td> <td>0 to 50,000 ft (15,240 m)</td> </tr> </table>	Operating	0 to 10,000 ft (3,048 m)	Non-operating	0 to 50,000 ft (15,240 m)
Operating	0 to 10,000 ft (3,048 m)				
Non-operating	0 to 50,000 ft (15,240 m)				
LED Activity	LED Amber – Radio OFF LED Off – Radio ON				

HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth® Specification 4.0/4.1/4.2/5.0 Compliant

Technical Specifications

Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate* throughput up to 2.17 Mbps BLE: 1 Mbps signaling data rate* throughput up to 0.2 Mbps * Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth® Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi® 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi® 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Wi-Fi® supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160 MHz channels.

Technical Specifications

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
3. Check latest software/driver release for updates on supported security features.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Realtek RTL8852AE 802.11ax¹ 2x2 Wi-Fi[®] + Bluetooth[®] 5.1 (802.11ax 2x2, supporting gigabit data rate)⁵	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi [®] certified modules
	Frequency Band	<ul style="list-style-type: none"> •802.11b/g/n/ax 2.402 – 2.482 GHz •802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	<ul style="list-style-type: none"> • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: max 300Mbps • 802.11ac : max 866.7Mbps • 802.11ax : max 1201Mbps
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security³	<ul style="list-style-type: none"> • IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • WPA3 certification • IEEE 802.11i • WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)

Technical Specifications

Roaming	IEEE 802.11 compliant roaming between access points	
Output Power²	<ul style="list-style-type: none"> • 802.11b : +18.5dBm minimum • 802.11g : +17.5dBm minimum • 802.11a : +18.5dBm minimum • 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum • 802.11n HT20(5GHz) : +15.5dBm minimum • 802.11n HT40(5GHz) : +14.5dBm minimum • 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ax HE40(2.4GHz) : +10dBm minimum • 802.11ax HE80(5GHz) : +10dBm minimum 	
Power Consumption	<ul style="list-style-type: none"> • Transmit mode :2.5 W • Receive mode :2 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode :50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW 	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity⁴	<ul style="list-style-type: none"> •802.11b, 1Mbps : -93.5dBm maximum •802.11b, 11Mbps : -84dBm maximum •802.11a/g, 6Mbps : -86dBm maximum •802.11a/g, 54Mbps : -72dBm maximum •802.11n, MCS07 : -67dBm maximum •802.11n, MCS15 : -64dBm maximum •802.11ac, MCS0 : -84dBm maximum •802.11ac, MCS9 : -59dBm maximum •802.11ax, MCS11(HE40): -57dBm maximum •802.11ax, MCS11(HE80): -54dBm maximum 	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure	
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	<ol style="list-style-type: none"> 1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm 	
Weight	<ol style="list-style-type: none"> 1. Type 2230: 2.8g 2. Type 126: 1.3g 	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating	14° to 158° F (-10° to 70° C)
	Non-operating	-40° to 176° F (-40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)

Technical Specifications

LED Activity	LED Amber – Radio OFF LED Off – Radio ON
---------------------	---

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.1 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo

Technical Specifications

Limited High Duty Cycle Non-Connectable Advertising
 2Mbps LE
 LE Long Range

1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for Wi-Fi® 6 (802.11ax WLAN) are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.
2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
3. Check latest software/driver release for updates on supported security features.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
5. Wi-Fi® supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160MHz channels.

Intel® XMM™ 7360 LTE-Advanced	Technology/Operating bands	<p>FDD LTE: LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12), 700 (Band 13) 700 (Band 17), 850 (Band 18), 850 (Band 19), 800 (Band 20), 1450 (Band 21), 850 (Band 26) 700 (Band 28) MHz, 700 (Band 29), 2300 (Band 30), 2100 (Band 66) MHz</p> <p>TDD LTE: 2600 (Band 38), 1900 (Band 39), 2300 (Band 40), 2500 (Band 41) MHz</p> <p>HSPA+: 2100 (Band 1), 1900 (Band 2), 1700 (Band 4), 850 (Band 5), 900 (Band 8) MHz</p>
	Wireless protocol standards	3GPP Release 11 LTE Specification CAT.9, MAX 60MHz aggregation BW WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone, A-GPS (MS-B and LTO)
	GPS bands	GPS 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 ± 2.046 MHz
	Maximum data rates	LTE: 450 Mbps (DL 3CA), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
	Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
	Form Factor	M.2, 3042-S3 Key B
	Weight	6 g
	Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

 Technical Specifications

Realtek RTK8111EPH 10/100/1000 Integrated NIC	Connector	RJ-45
	System Interface	PCIe + SMBus
	Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
	Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
	Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Management Interface	Auto MDI/MDIX Crossover cable detection
	IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Security & Manageability	RTK DASH support with appropriate RTK chipset components

Technical Specifications

POWER

AC Adapter 45 Watt nPFC Standard USB Type-C® Straight 1.8m	Dimensions (H x W x D)	94.0mm x 40.0mm x 26.5mm
	Weight	192.5g +/-10%
	Input	Input Efficiency Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 12V: 87.41% 15V: 87.8%
		Input frequency range 47 ~ 63 Hz
		Input AC current Max. 1.4 A at 90 Vac
	Output	Output power 5V/15W 9V/27W 12V/36W 15V/45W
		DC output 5V/9V/12V/15V
		Hold-up time 5 ms at 115 Vac input
	Connector	USB Type-C®
	Environmental Design	Operating temperature 32°F to 95°F (0° to 35°C) Non-operating (storage) temperature -4°F to 185°F (-20° to 85°C) Altitude 0 to 16,400 ft (0 to 5,000 m) Humidity 20% to 95% Storage Humidity 10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5mm Right Angle 1.8m	Dimensions	95 x 45 x 26.8 mm
	Weight	200 g +/- 10 g
	Input	Input Efficiency 87.74 % at 115 Vac and 88.4 % at 230Vac
		Input frequency range 47 ~ 63 Hz
		Input AC current Max. 1.4 A at 90 Vac
	Output	Output power 45 W
		DC output 19.5 V
		Hold-up time 5 ms at 115 Vac input
		Output current limit <8.0A
	Connector	4.5mm Barrel Type

Technical Specifications

Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
	Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5mm Right Angle 1.8m 2prong	Dimensions	95 x 45 x 26.8 mm	
	Weight	200 g +/- 10 g	
	Input	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230 Vac
		Input frequency range	47 ~ 63 Hz
	Output	Input AC current	Max. 1.4 A at 90 Vac
		Output power	45 W
		DC output	19.5 V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<8.0A
	Connector	4.5mm Barrel Type	
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
Humidity		20% to 95%	
Storage Humidity		10% to 95%	
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.		

Technical Specifications

AC Adapter 65 Watt nPFC Standard USB Type-C® Straight 1.8m	Dimensions	90.0 x 51 x 28.5mm		
	Weight	250 g +/- 10 g		
	Input	Input Efficiency	81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A	
		Input frequency range	47 ~ 63 Hz	
		Input AC current	1.6 A at 90 VAC and maximum load	
		Output	Output power	65 W
			DC output	5V/9V/12V/15V/20V
	Hold-up time		5 ms at 115 Vac input	
	Connector	USB Type C®		
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)	
		Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)	
		Altitude	0 to 16,400 ft (0 to 5000m)	
		Humidity	20% to 95%	
		Storage Humidity	10% to 95%	
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.			

AC Adapter 65 Watt Smart nPFC EM Barrel 4.5mm New EM	Dimensions (H x W x D)	102 x 55 x 30mm	
	Weight	250g +/-10%	
	Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230 Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.7 A at 90 Vac
	Output	Output power	65W
		DC output	19.5V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<11.0A
	Connector	4.5mm Barrel Type	
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)

Technical Specifications

EMI and Safety Certifications	Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
	Altitude	0 to 16,400 ft (0 to 5,000 m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
	EMI and Safety Certifications	

AC Adapter 65 Watt Smart nPFC Standard Barrel 4.5mm Right Angle 1.8m

Dimensions (H x W x D)	90 x 51 x 28.5mm	
Weight	230g +/-10%	
Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230 Vac
	Input frequency range	47 ~ 63 Hz
	Input AC current	Max. 1.7 A at 90 Vac
Output	Output power	65W
	DC output	19.5V
	Hold-up time	5 ms at 115 Vac input
	Output current limit	<11.0A
Connector	4.5mm Barrel Type	
Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
	Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
	Altitude	0 to 16,400 ft (0 to 5,000 m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

Technical Specifications

Battery RH 3 Cell WHr 45 Long Life -PL Fast Charge	Dimensions (H x W x L)	6.2 x 68.7 x 249.6mm
	Weight	190g
	Cells/Type	3cell Lithium-Ion Polymer cell/ 545974
	Voltage	11.4 V
	Amp-hour capacity	3.950Ah
	Watt-hour capacity	45 Wh
	Operating (Charging)	32° to 113° F (0° to 45° C)
	Operating (Discharging)	14° to 122° F (-10° to 60° C)
	Optional Travel Battery Available	No
	Warranty	Based on system offering

Country of Origin

China

QuickSpecs

Options and Accessories (sold separately and availability may vary by country)

Type	Description	Part Number
Cases	HP Business Backpack (up to 17.3")	2SC67AA
	HP Business Slim Top Load (up to 14.1")	2SC65AA
	HP Prelude Pro Recycle Backpack	1X644AA
	HP Prelude Pro Recycle Top Load	1X645AA
	HP Recycled Top Load	5KN29AA
	HP Recycled Backpack	5KN28AA
Docking	HP USB-C® Mini Dock	1PM64AA
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP TB Dock G2 w/ Combo Cable	3TR87AA
	HP TB Dock 120W G2 w/Audio	3YE87AA
	HP TB Dock 120W G2 Cable	3XB94AA
	HP TB Dock G2 Combo Cable	3XB96AA
	HP TB Dock G2 Audio Module	3AQ21AA
	HP USB-C/A Universal Dock G2	5TW13AA
	HP USB-C Dock G5	5TW10AA
Input/Output	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Wired Desktop 320MK Mouse & Keyboard	9SR36AA
	HP Bluetooth® Travel Mouse	6SP30AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP Wired Desktop 320M Mouse	9VA80AA
	HP USB Travel Mouse	G1K28AA
	HP Elite USB-C Hub	4WX89AA
	HP USB-C Travel Hub G2	7PJ38AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
	HP Stereo USB Headset	T1A67AA
	HP Stereo 3.5mm Headset	T1A66AA
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	45W Smart Power Adapter 2 prong -4.5mm (Japan only)	L6F60AA
	65W Smart Power Adapter (w/ 4.5mm to 7.5mm DC dongle)	H6Y89AA
	HP 65W Slim AC Adapter	H6Y82AA
	HP 65W USB-C Slim Power Adapter	3PN48AA
	HP 45W LC USB-C Power Adapter	1MZ01AA
	HP 65W USB-C LC Power Adapter	TBD



QuickSpecs

Options and Accessories (sold separately and availability may vary by country)

	HP Power Bank	N9F71AA
	HP USB-C Notebook Power Bank	3TB55AA
Memory	HP 4GB DDR4 3200 Memory	286H5AA
	HP 8GB DDR4 3200 Memory	286H8AA
	HP 16GB DDR4 3200 Memory	286J1AA
Storage	HP External USB Optical Drive	F2B56AA
Security	HP Sure Key Cable Lock	6UW42AA
	HP Nano Keyed Cable Lock	1AJ39AA



Summary of Changes

Date of change:	Version History:		Description of change:
December 14, 2020	V1 to V2	Update	USB Information
January 17, 2021	V2 to V3	Update	Environmental Data
January 26, 2021	V3 to V4	Added	New Processors and USB Ports
January 29, 2021	V4 to V5	Update	USB Ports
February 2, 2021	V5 to V6	Update	Noise Emissions Data
February 25, 2021	V6 to V7	Update	Xerox DocuShare offer value
April 6, 2021	V7 to V8	Removed	Interchangeable HDD
April 20, 2021	V8 to V9	Updated	Memory Section Updated
April 29, 2021	V9 to V10	Added	Realtek WLAN/Updated TPM 2.0

Copyright © 2021 HP Development Company, L.P. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

Intel®, Core®, and Intel vPro® are trademarks or registered trademarks of Intel Corporation or its subsidiaries in the United States and other countries. Bluetooth® is a trademark owned by its proprietor and used by HP Inc. under license. USB Type-C® and USB-C® are trademarks of USB Implementers Forum. ENERGY STAR is a registered trademark of the U.S. Environmental Protection Agency. Microsoft and Windows are trademarks or registered trademarks of Microsoft Corporation in the U.S. and/or other countries